

MOSFET

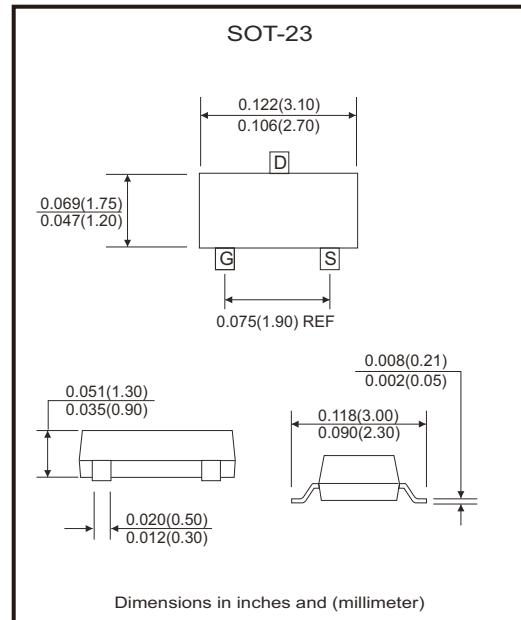
Comchip
SMD Diode Specialist

CMS3407T-HF

P-Channel
RoHS Device
Halogen Free



V(BR)DSS	RDS(on)MAX	ID
-30V	50mΩ @ -10V	-4.1A
	75mΩ @ -4.5V	



Features

- Advanced high cell density trench technology.
- Low $R_{DS(ON)}$
- Low gate charge.
- Green device available.

Mechanical data

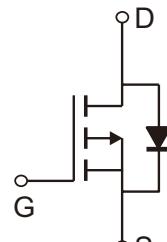
- Case: SOT-23, molded plastic.

Description

The CMS3407T is the highest performance trench P-ch MOSFETs with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for use as a load switch or in PWM applications. The CMS3407T meet the RoHS and Green Product requirement with full function reliability approved.

Circuit Diagram

- G : Gate
- S : Source
- D : Drain



Maximum Ratings (at $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source voltage	V_{DS}	-30	V
Gate-Source voltage	V_{GS}	± 20	V
Continuous drain current ³	$I_D @ T_a=25^\circ\text{C}$	-4.1	A
	$I_D @ T_a=70^\circ\text{C}$	-3.5	A
Pulsed drain current ^{1,2}	$I_{DM} @ T_a=25^\circ\text{C}$	-12	A
Total power dissipation	$P_D @ T_a=25^\circ\text{C}$	1.38	W
Linear derating factor	-	0.01	W/ $^\circ\text{C}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 ~ +150	$^\circ\text{C}$

Thermal Data

Parameter	Symbol	Max. Value	Unit
Thermal resistance junction-ambient ³	$R_{\theta JA}$	90	$^\circ\text{C}/\text{W}$

Electrical Characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source breakdown voltage	BV_{DSS}	-30			V	$\text{V}_{\text{GS}}=0, \text{I}_D=-250\mu\text{A}$
Gate threshold voltage	$\text{V}_{\text{GS(th)}}$	-1.0		-3.0	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=-250\mu\text{A}$
Forward transconductance	g_{fs}		8.2		S	$\text{V}_{\text{DS}}=-5\text{V}, \text{I}_D=-4\text{A}$
Gate-Source leakage current	I_{GSS}			± 100	nA	$\text{V}_{\text{GS}}= \pm 20\text{V}$
Drain-Source leakage current ($T_J=25^\circ\text{C}$)	I_{DSS}			-1	μA	$\text{V}_{\text{DS}}=-24\text{V}, \text{V}_{\text{GS}}=0$
Drain-Source leakage current ($T_J=55^\circ\text{C}$)				-5		$\text{V}_{\text{DS}}=-24\text{V}, \text{V}_{\text{GS}}=0$
Static drain-source on-resistance ²	$\text{R}_{\text{DS(ON)}}$			50	$\text{m}\Omega$	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-4.1\text{A}$
				75		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-3.0\text{A}$
Total gate charge ²	Q_g		15.2		nC	$\text{I}_D=-3\text{A}$ $\text{V}_{\text{DS}}=-24\text{V}$ $\text{V}_{\text{GS}}=-10\text{V}$
Gate-Source charge	Q_{gs}		5.5			
Gate-Drain ("Miller") charge	Q_{gd}		1			
Turn-on delay time ²	$\text{T}_{\text{d(on)}}$		8.6		ns	$\text{V}_{\text{DS}}=-15\text{V}$ $\text{I}_D=-1\text{A}$ $\text{V}_{\text{GS}}=-10\text{V}$ $\text{R}_G=6\Omega$ $\text{R}_D=15\Omega$
Rise time	T_r		12.2			
Turn-off delay time	$\text{T}_{\text{d(off)}}$		36.6			
Fall time	T_f		20.8			
Input capacitance	C_{iss}		590		pF	$\text{V}_{\text{GS}}=0\text{V}$ $\text{V}_{\text{DS}}=-25\text{V}$ $f=1.0\text{MHz}$
Output capacitance	C_{oss}		75			
Reverse transfer capacitance	Crss		10			

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Diode forward voltage ²	V_{SD}			-1.2	V	$\text{I}_S=-1.0\text{A}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=25^\circ\text{C}$
Continuous source current	I_S			-4.1	A	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current

Notes: 1. Pulse width limited by Max. junction temperature.
 2. Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
 3. Surface mounted on 1 in² copper pad of FR4 board; 270°C/W when mounted on min. copper pad.

Rating and Characteristic Curves

TYPICAL CHARACTERISTIC

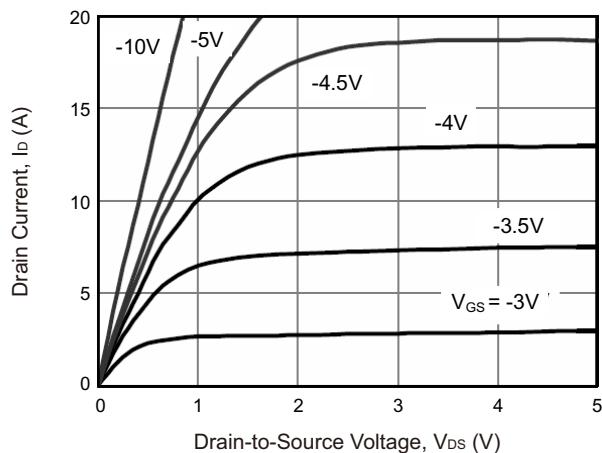


Fig.1 - Typical Output Characteristics

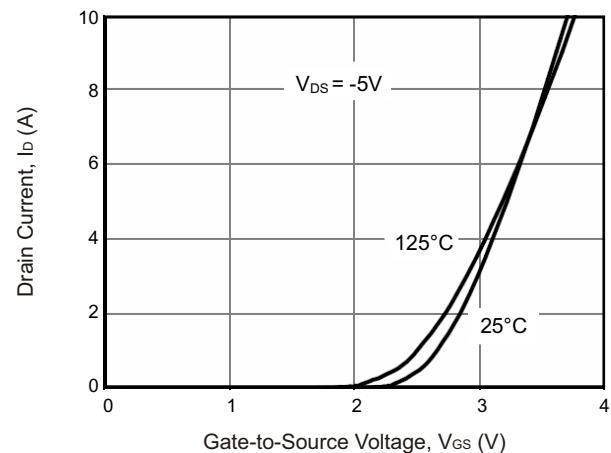


Fig.2 - Transfer Characteristics

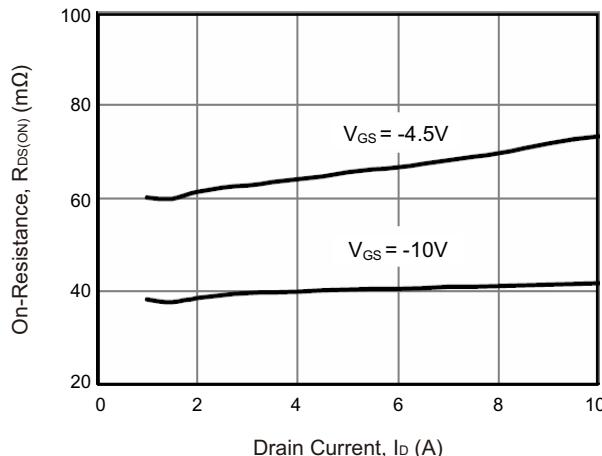


Fig.3 - On-Resistance vs. Drain Current

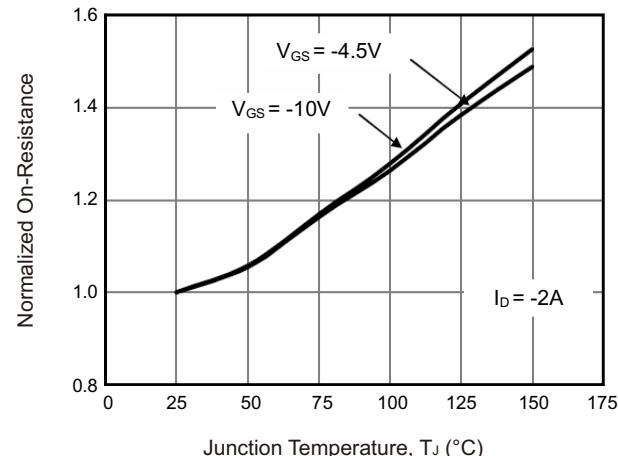


Fig.4 - Normalized $R_{DS(ON)}$ vs. T_J

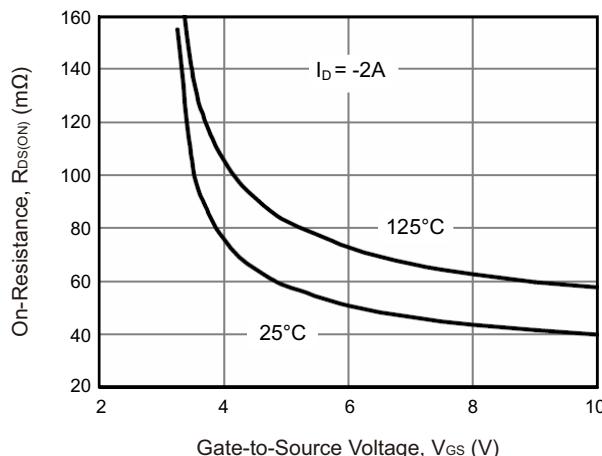


Fig.5 - On-Resistance vs. G-S Voltage

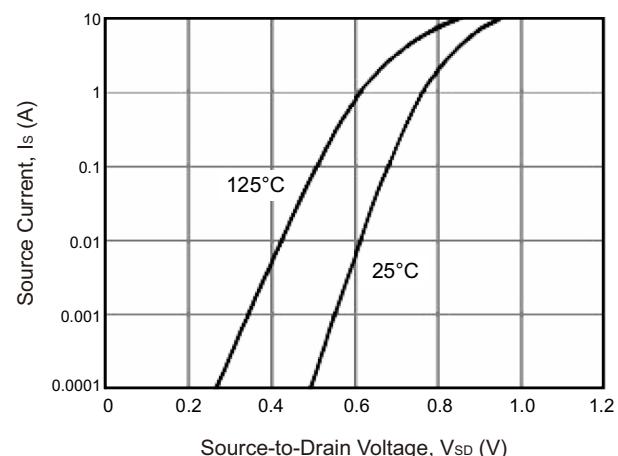
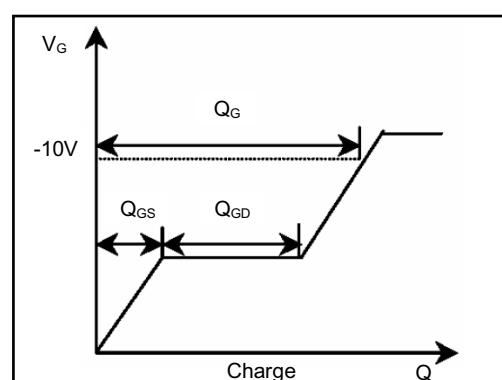
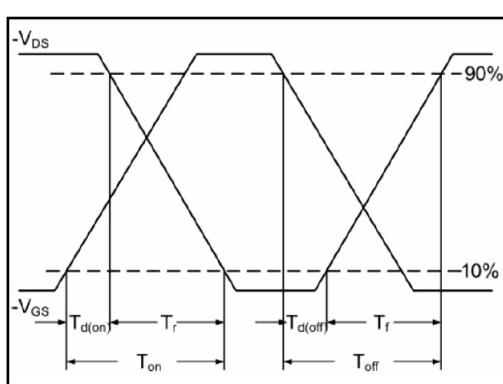
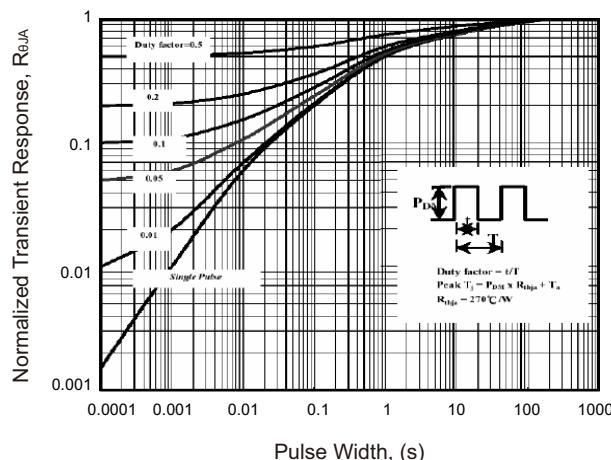
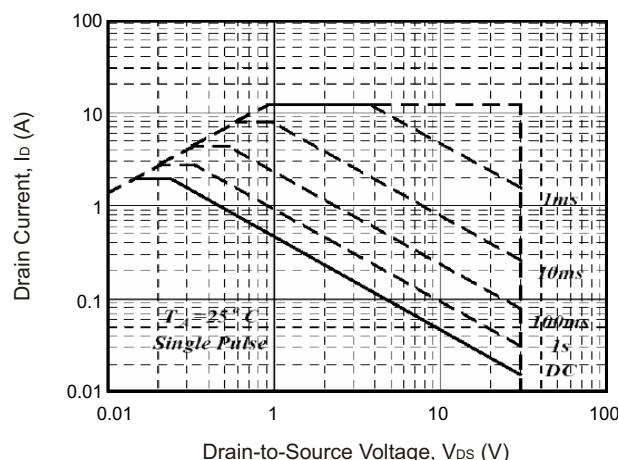
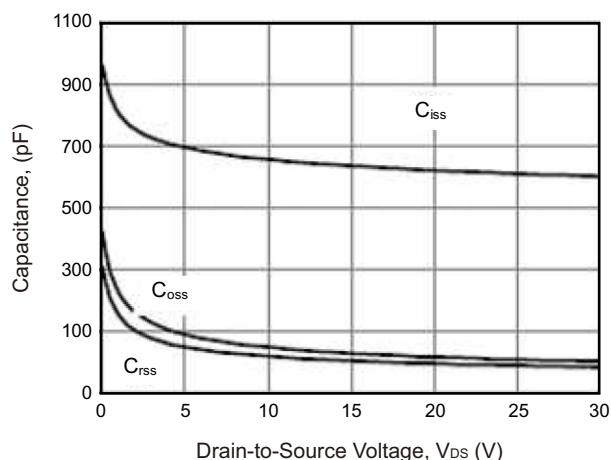
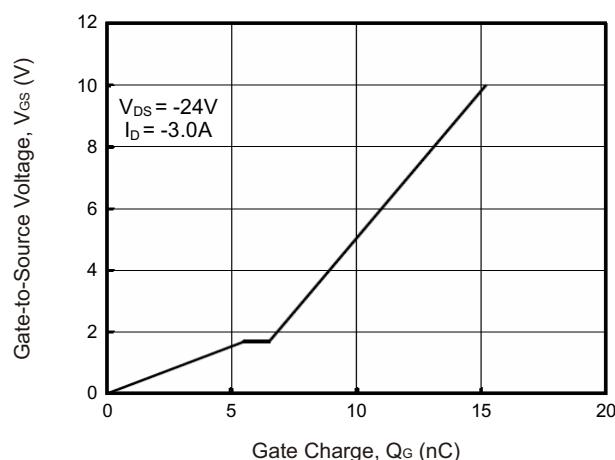
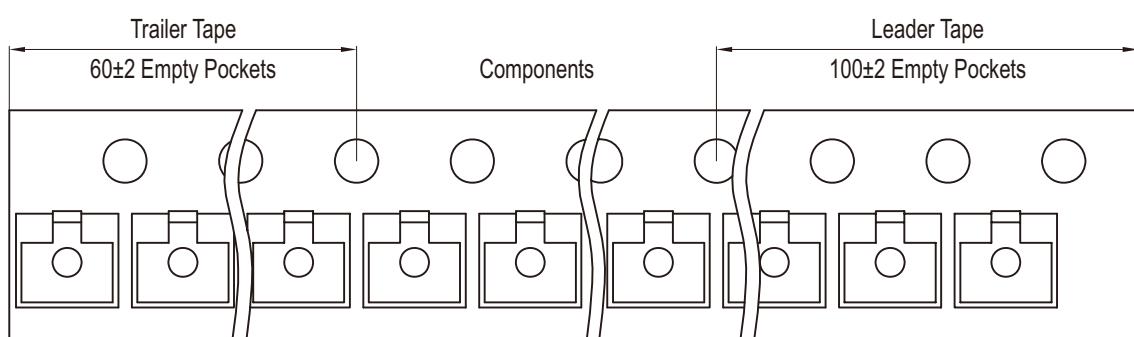
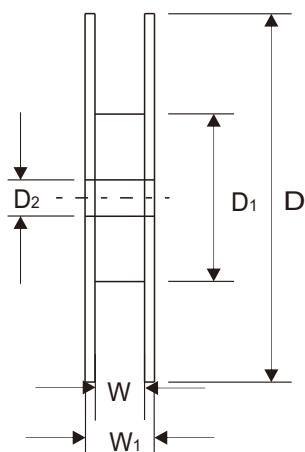
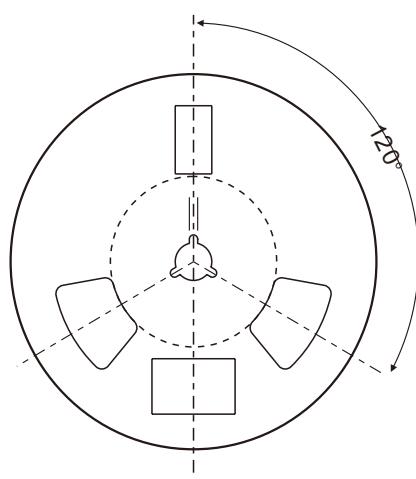
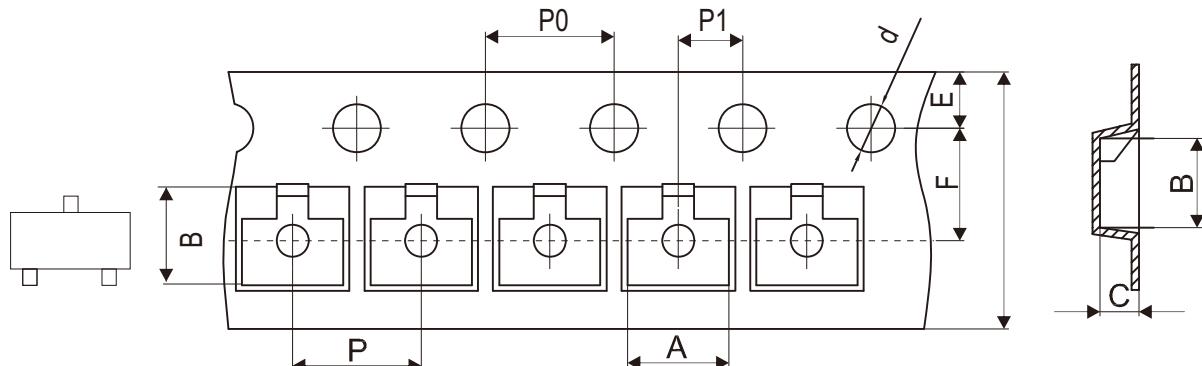


Fig.6 - Forward Characteristics of Reverse



Reel Taping Specification

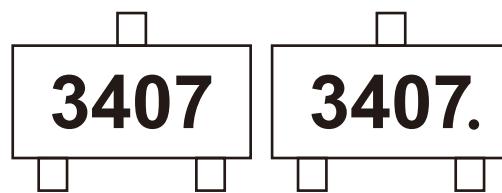


SOT-23	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	3.10 ± 0.10	3.20 ± 0.10	1.37 ± 0.10	1.50 ± 0.10	178.00 ± 2.00	54.40 ± 1.00	13.00 ± 1.00
	(inch)	0.122 ± 0.004	0.126 ± 0.004	0.054 ± 0.004	0.059 ± 0.004	7.008 ± 0.079	2.142 ± 0.039	0.512 ± 0.039

SOT-23	SYMBOL	E	F	P	P0	P1	W	W1
	(mm)	1.75 ± 0.10	3.50 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	$8.40 + 1.50 / - 0.50$	12.00 ± 1.50
	(inch)	0.069 ± 0.004	0.138 ± 0.004	0.157 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	$0.330 + 0.012 / - 0.004$	0.472 ± 0.039

Marking Code

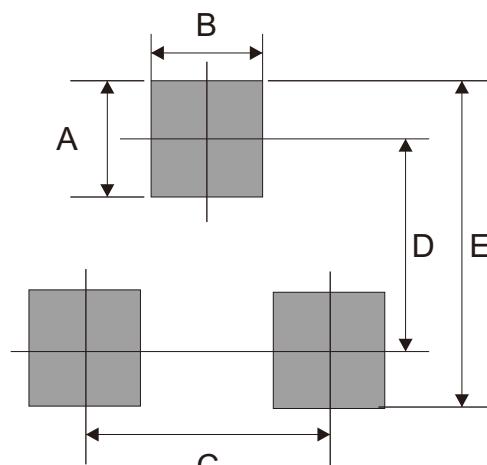
Part Number	Marking Code
CMS3407T-HF	3407



Solid dot = Control code

Suggested P.C.B. PAD Layout

SIZE	SOT-23	
	(mm)	(inch)
A	0.80	0.031
B	0.60	0.024
C	2.20	0.087
D	2.37	0.093
E	2.97	0.117



Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
SOT-23	3,000	7